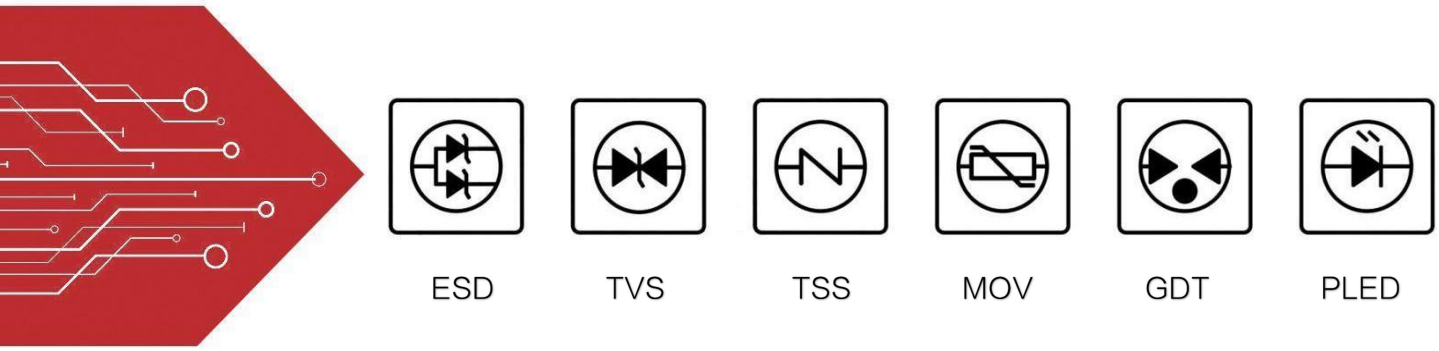
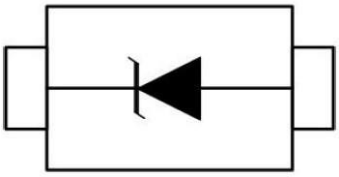
MSKSEMI
SEMICONDUCTOR



Product data sheet



- 350 Watts peak pulse power (tp = 8/20μs)
- Transient protection for high speed data lines to
  IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
  IEC 61000-4-4 (EFT) 40A (5/50ns)
- Working voltages : 3.3V-36V
- Protects one bidirectional line
- Low operating and clamping voltages
- Solid-state silicon avalanche technology



SOD-323

Applications

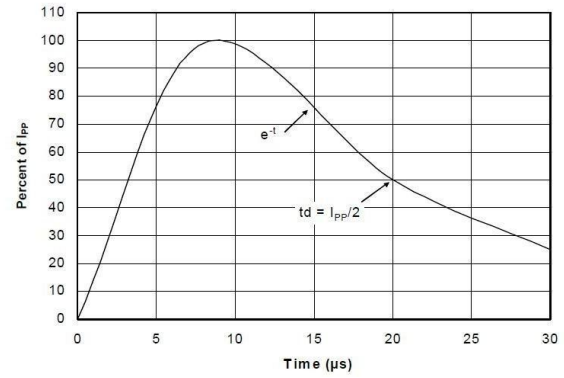
- Notebooks, Desktops, Servers and Video Graphics Cards
- USB Power & Data Line Protection
- Monitors and Flat Panel Displays
- I²C Bus Protection
- Portable Instrumentation
- Set Top Box

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	±15 ±8	kV
P_{PP}	Peak Pulse Power (8/20μs)	350	W
T_{OPT}	Operating Temperature	-55/+150	°C
T_{STG}	Storage Temperature	-55/+150	°C
T_L	Lead Soldering Temperature	260 (10 sec.)	°C

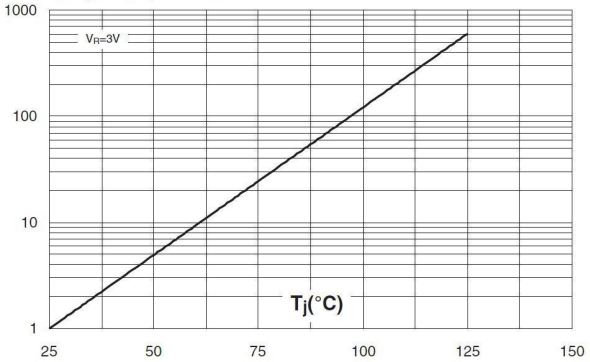
P/N	V_{RWM} (V) (max.)	V_B (V) (min.)	I_T (mA)	V_C@1A (V) (max.)	V_C (V) (max.)	(@A)	I_R (μA) (max.)	C_T (pF) (max.)
ESD3Z5.0T1G-MS	5	6	1	9.8	18	17	10	300

ypical Characteristics@ Ta=25℃ unless otherwise specified

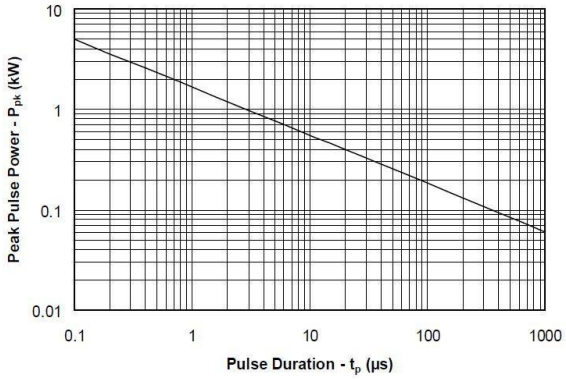
Pulse Waveform



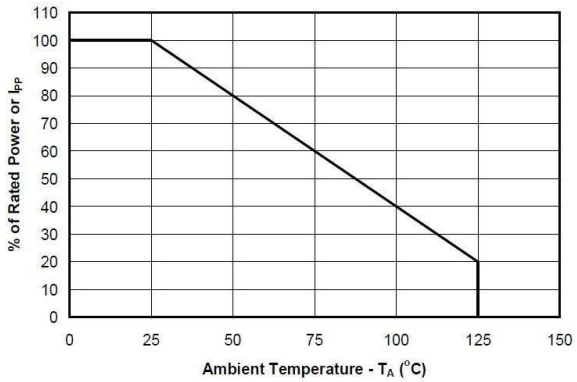
$I_R[T_j]$ / $I_R[T_j=25°C]$



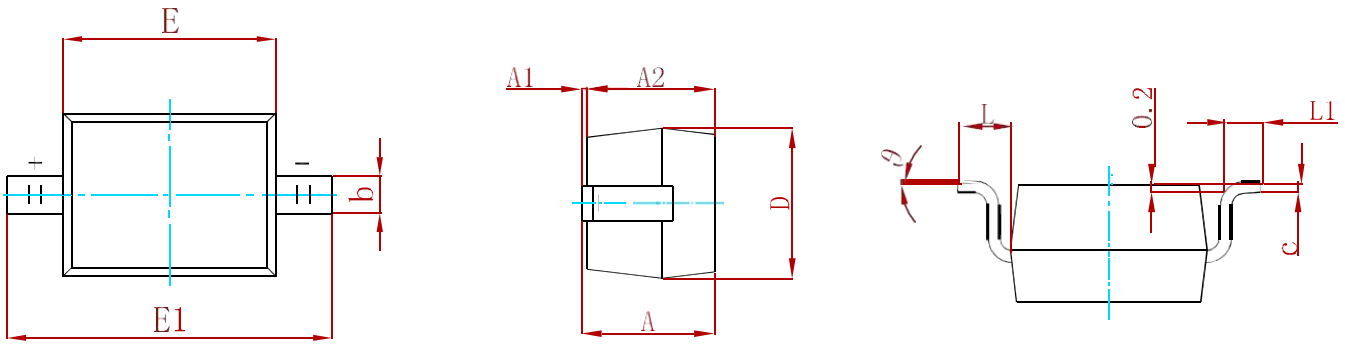
Non-Repetitive Peak Pulse Power vs. Pulse Time



Power Derating Curve

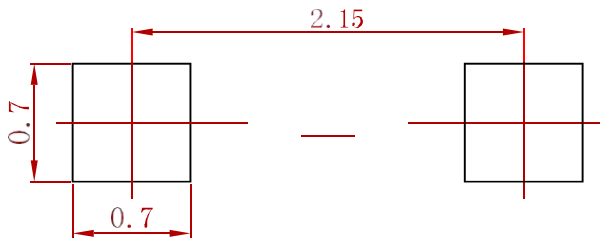


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESD3Z5.0T1G-MS	SOD-323	3000

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